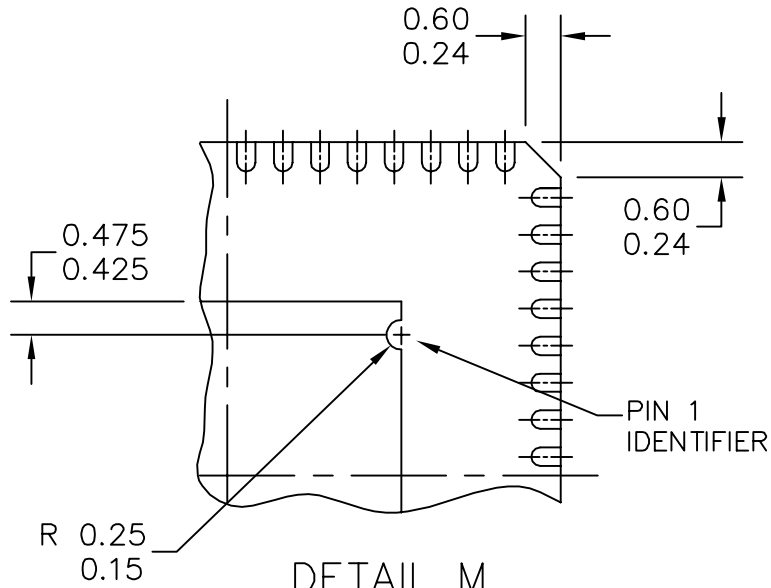
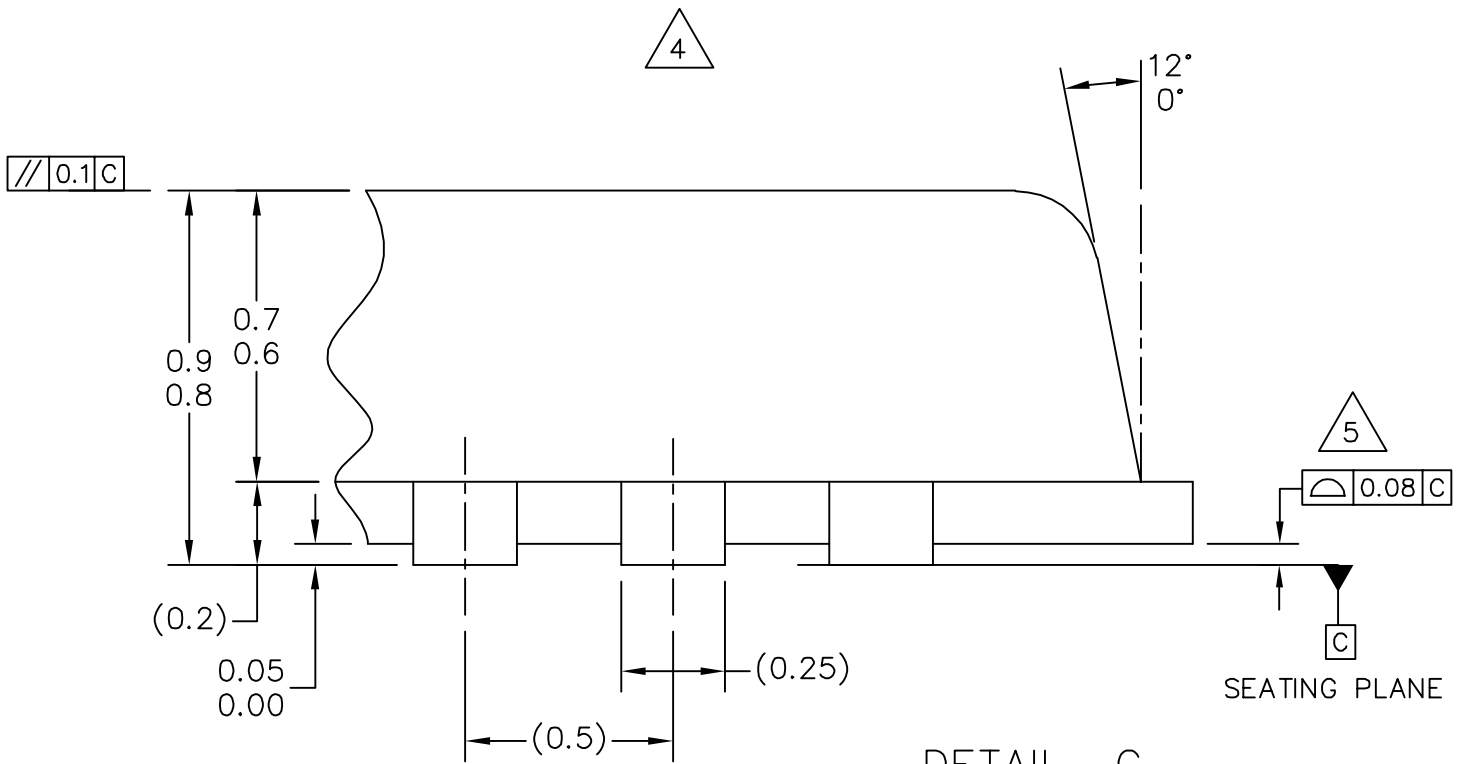


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| TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 64 TERMINAL, 0.5 PITCH (9 X 9 X 0.9) | | DOCUMENT NO: 98ARS10519D | REV: A |
| | | CASE NUMBER: 1606-01 | 21 JUL 2006 |
| STANDARD: NON-JEDEC | | | |



DETAIL M
PIN 1 BACKSIDE IDENTIFIER



DETAIL G
VIEW ROTATED 90° CW

| | | | |
|---|---------------------------|----------------------------|--|
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| | STANDARD: NON-JEDEC | | |

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4. CORNER CHAMFER MAY NOT BE PRESENT.
5. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
6. MINIMUM GAP BETWEEN METAL SHOULD BE 0.2 MM.

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